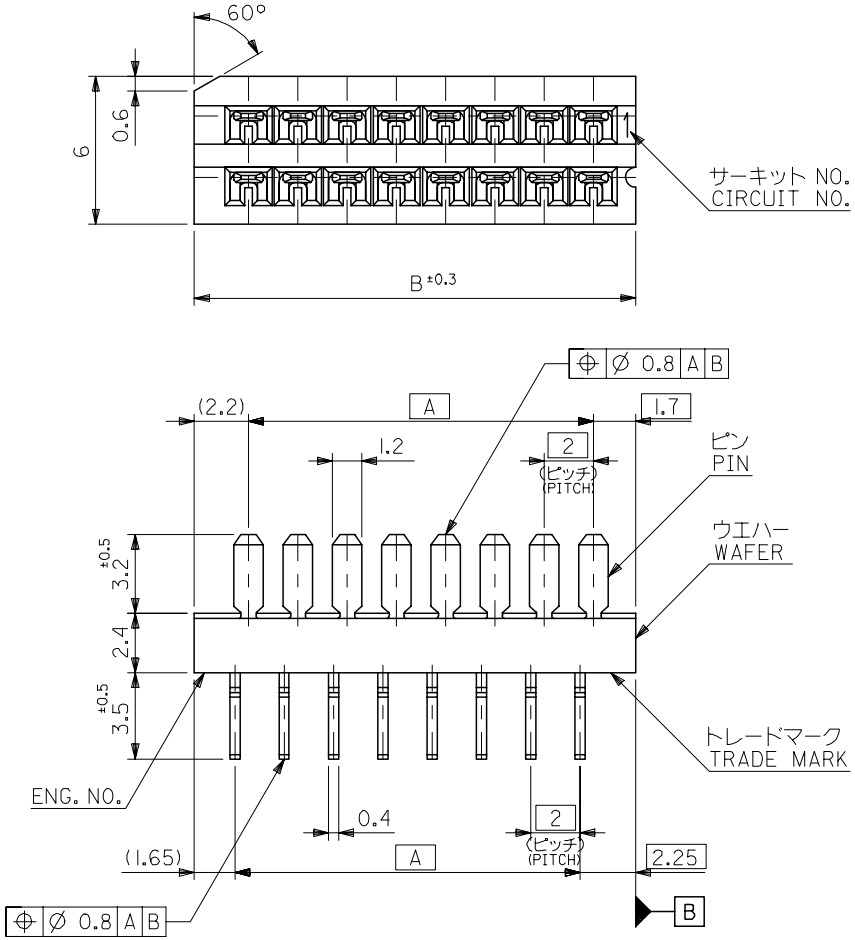

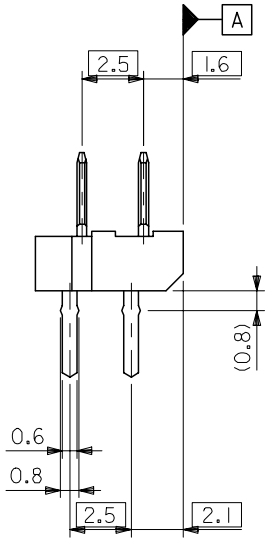

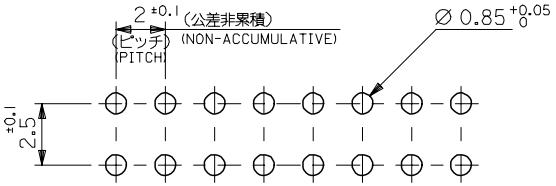

基板取付穴推奨寸法（基板厚： 1.6）
RECOMMENDED P. C. BOARD HOLE DIM. (THICKNESS: 1.6)

注記 NOTES

1. 嵌合相手：5533シリーズ。
   MATES WITH : 5533 SERIES.
2. メス側との基板取付穴のズレについては
   図面 SD-5533-NCPB を参照のこと。
   REFFER TO SD-5533-NCPB DRAWING
   FOR P. C. BOARDS POSITIONING DIMENSIONS.
3. 材質 MATERIAL
   ピン：黄銅 (t0.4) ニッケル下地 錫メッキ
   ウエハー：ナイロン66、UL94V-0
   PIN : BRASS(t0.4), TIN OVER NICKEL PLATED
   WAFER : NYLON66, UL94V-0
4. 本製品は 5532-NA の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 5532-NA.

B	A	EDP. NO.	ENG NO.	極数 NO. OF CKT.
41.9	38	39-35-1409	5532-40A7F	40
39.9	36	-1389	-38A7F	38
37.9	34	-1369	-36A7F	36
35.9	32	-1349	-34A7F	34
33.9	30	-1329	-32A7F	32
31.9	28	-1309	-30A7F	30
29.9	26	-1289	-28A7F	28
27.9	24	-1269	-26A7F	26
25.9	22	-1249	-24A7F	24
23.9	20	-1229	-22A7F	22
21.9	18	-1209	-20A7F	20
19.9	16	-1189	-18A7F	18
17.9	14	-1169	-16A7F	16
15.9	12	-1149	-14A7F	14
13.9	10	-1129	-12A7F	12
11.9	8	-1109	-10A7F	10
9.9	6	-1089	-08A7F	8
7.9	4	-1069	-06A7F	6
5.9	2	39-35-1049	5532-04A7F	4

REVISED
EC NO: J2005-2412 2005/02/23
DRWN:MNABEI 2005/02/24
CHKD:KTOJO 2005/03/01
APPR:NUKITA
DESCRIPTION
REV A

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: M.NINOMIYA DATE: '04/03/16
CHECKED BY: K.TOJO DATE: '04/03/16
APPROVED BY: M.SASAO DATE: '04/03/16

TITLE: 2.0 BOARD TO BOARD CONN WAFER ASSY -LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-5532-001
SHEET NO.: 1 OF 1
SIZE: A3

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